C5909A

Conductor

Description

C5909A is a gold paste designed as a hole plug in alumina substrates. The high solids loading allows for excellent filling properties with Bladder Fills. C5909A has low shrinkage, which allows for a complete fill of the through hole.

Key Features

- High solids loading Low shrinkage For use with Bladder Fills

This picture does not show the packaging of C5909A and is solely intended for illustration purposes. The products are available in different packaging configurations and may change over time. Please refer to the latest safety data sheets for safety-relevant pictograms.

Typical Properties	
Conductivity	≤ 25 milliohms/square at 25 um fired film thickness
Viscosity	600 – 1000 Kcps Brookfield HBTSC4 – 14 spindle and 6R utility cup at 10 rpm, 25 °C
Solids	95.0 ± 1.0 %
Metal	Au

Recommended Processing Guide	
Drying Temperature	150 °C for 15 minutes
Process Temperature (TDS)	850 °C peak temperatureDwell time 8 – 12 minutes

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Warranty

6 months

Storage

Store in a dry location at 5°C-25°C

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